

**SERIES 620 LCC SOCKET, 2.85mm
AUTOMATIC ASSEMBLY**
**621 LCC SOCKET, 2.85mm
MANUAL ASSEMBLY**

FOR JEDEC TYPE C DEVICE

PATENTED

SMD

**HI-REL SURFACE MOUNT 32 PIN
ULTRA LOW PROFILE LEADLESS CHIP CARRIER SOCKET**

FEATURES

- .112 in [2.85 mm] HEIGHT ABOVE BOARD
SAME HEIGHT AS UNSOCKETED DEVICE
- ACCEPTS JEDEC TYPE C DEVICES
.050 in [1.27 mm] PITCH, MOUNTS ON EXISTING
FOOT-PRINT
- DESIGNED FOR HIGH DENSITY APPLICATIONS WHERE
SPACE ON & ABOVE PCB IS CRITICAL
- 220°C INSULATOR MATERIAL WITHSTANDS HIGH
TEMPERATURE SOLDER PROCESS
- UNIQUE BeCu CONTACT DESIGN ALLOWS SECURE
RETENTION OF DEVICE
- OPTIONAL RETENTION CLIP AVAILABLE FOR HIGH
SHOCK APPLICATIONS
- SPECIFICALLY DESIGNED FOR MOBILE/CELLULAR PHONE
AND DISK DRIVE APPLICATIONS

**NOTE: VACUUM PICKUP BAR IS DESIGNED TO BE
TWISTED OFF BY HAND AFTER SOLDERING**

TECHNICAL SPECIFICATIONS

ELECTRICAL DATA

CONTACT RESISTANCE: 30 MILLIOHMS MAX.
CURRENT RATING: 1.0 AMP
INSULATION RESISTANCE: 1000 MEGAOHMS MIN.
DIELECTRIC VOLTAGE: 500 VAC

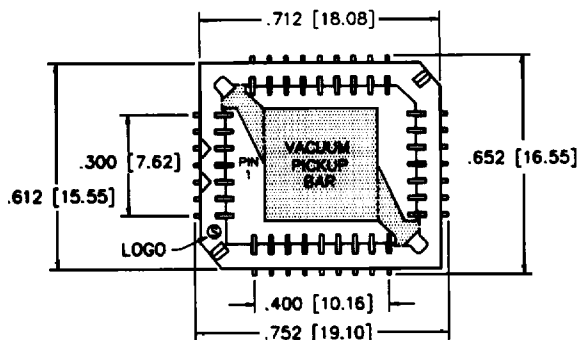
MATERIAL DATA

INSULATOR: HIGH TEMP NYLON 46, UL94V-0
CONTACT: BERYLLIUM COPPER
PLATING: GOLD OVER NICKEL

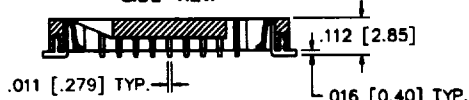
WILL ACCEPT THE FOLLOWING DEVICES	
AMD	M27C010-155LC
ATMEL	AT27C010
CATALYST	CAT27C2000E1-25
FUJITSU	276512-15
WSI	WS272561-90

620 SERIES

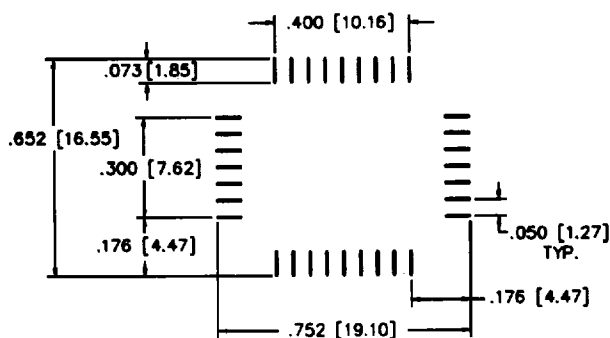
TOP VIEW



SIDE VIEW

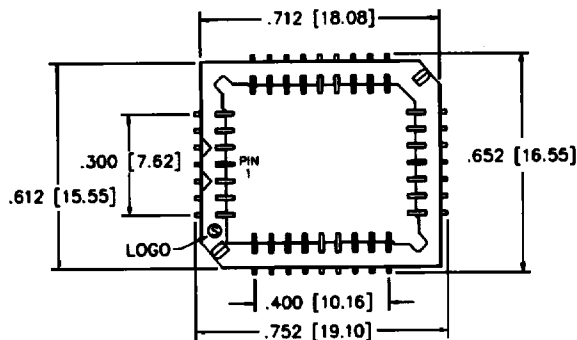


PC BOARD FOOTPRINT

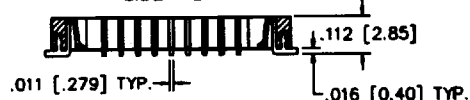


621 SERIES

TOP VIEW



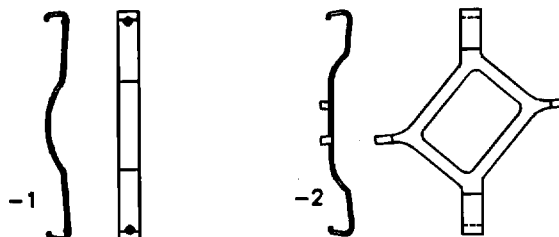
SIDE VIEW



ORDERING INFORMATION

62X-32-SM-G10-S12-X
620 SERIES
621 SERIES
NO. OF CONTACTS
TYPE
SURFACE MOUNT
WHEN ORDERING WITH
OPTIONAL RETENTION CLIP
MATERIAL AND LOGO
CONTACT PLATING
GOLD OVER NICKEL

OPTIONAL RETENTION CLIP



P/N: CLL-32
WHEN ORDERING SEPARATELY

P/N: CLL-32-4
WHEN ORDERING SEPARATELY